Power MOSFET

-60 V, -12 A, Single P-Channel, TO-220

Features

- Low R_{DS(on)}
- Rugged Performance
- Fast Switching
- Pb-Free Package is Available*

Applications

- Industrial
- Automotive
- Power Supplies

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	-60	٧
Gate-to-Source Voltage			V_{GS}	±20	٧
Continuous Drain	Steady State	T _C = 25°C	I _D	-12	Α
Current (Note 1)	State	T _C = 85°C		-9.0	
Power Dissipation (Note 1)		T _C = 25°C	P _D	62.5	W
Continuous Drain	Steady	T _A = 25°C	I _D	-2.4	Α
Current (Note 1)	State	State T _A = 85°C		-1.8	
Power Dissipation (Note 1)		T _A = 25°C	P _D	2.4	W
Pulsed Drain Current	t _p =	: 10 μs	I _{DM}	-42	Α
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 175	°C
Source Current (Body Diode)			I _S	-12	Α
Single Pulse Drain-to-Source Avalanche Energy (V_{DD} = -30 V, V_{G} = -10 V, I_{PK} = -12 A, L = 3.0 mH, R_{G} = 3.0 Ω)			EAS	216	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case	$R_{\theta JC}$	2.4	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	62.5	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 When surface mounted to an FR4 board using 1 in pad size (Cu. area = 1.127 in sq [1 oz] including traces).

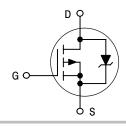


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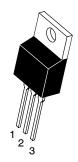
http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} Typ	I _D MAX	
-60 V	156 mΩ @ –10 V	-12 A	

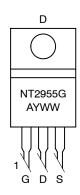
P-Channel



MARKING DIAGRAM & PIN ASSIGNMENT



TO-220 CASE 221A STYLE 5



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NTP2955	TO-220	50 Units / Rail
NTP2955G	TO-220 (Pb-Free)	50 Units / Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise stated)

Parameter	Symbol	Test Con	dition	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				•		•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				67		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			-1.0	μА
		$V_{GS} = 0 V$, $V_{DS} = -48 V$	T _J = 125°C			-10	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{G}$	_{iS} = ±20 V			±100	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= -250 μA	-2.0		-4.0	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				56		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = -10 \text{ V},$	I _D = -12 A		156	196	mΩ
Forward Transconductance	9FS	$V_{DS} = -60 \text{ V},$	I _D = -12 A		6.0		S
CHARGES AND CAPACITANCES	•				1		1
Input Capacitance	C _{ISS}				507	700	pF
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V, } f = 1.0 \text{ MHz,}$ $V_{DS} = -25 \text{ V}$			150	250	7
Reverse Transfer Capacitance	C _{RSS}				48	98	
Total Gate Charge	Q _{G(TOT)}				14		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = -10 V, V	V _{GS} = -10 V, V _{DS} = -48 V,		1.6	2.5	
Gate-to-Source Charge	Q _{GS}	$I_D = -12 \text{ A}$			3.4		
Gate-to-Drain Charge	Q_{GD}				6.2		
SWITCHING CHARACTERISTICS (No	ote 3)						
Turn-On Delay Time	t _{d(on)}				10	20	ns
Rise Time	t _r	V _{GS} = -10 V, V _{DD} = -30 V,			41	80	
Turn-Off Delay Time	t _{d(off)}	$I_{D} = -12 \text{A}, \text{R}$	_G = 9.1 Ω		27	47	
Fall Time	t _f	<u> </u>			45	85	
DRAIN-SOURCE DIODE CHARACTE	RISTICS		•		•		•
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C		-1.6	-2.0	V
		$I_{S} = -12 \text{A}$	T _J = 125°C		-1.36		
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A}/\mu\text{s,}$ $I_{S} = -12 \text{ A}$			53		
Charge Time	ta				42		ns
Discharge Time	t _b				12		
Reverse Recovery Charge	Q _{RR}				126		nC

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
Switching characteristics are independent of operating junction temperatures.

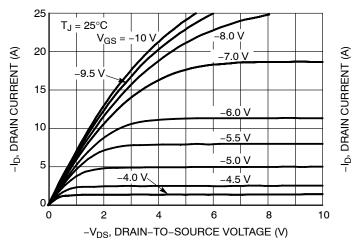


Figure 1. On-Region Characteristics

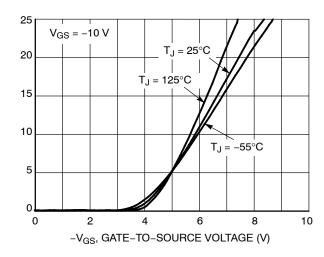


Figure 2. Transfer Characteristics

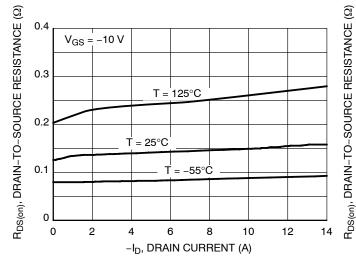


Figure 3. On-Resistance versus Drain Current and Temperature

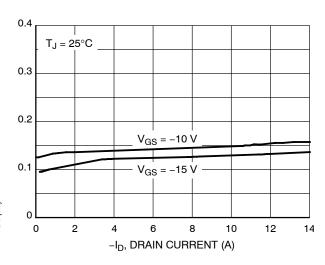


Figure 4. On-Resistance versus Drain Current and Gate Voltage

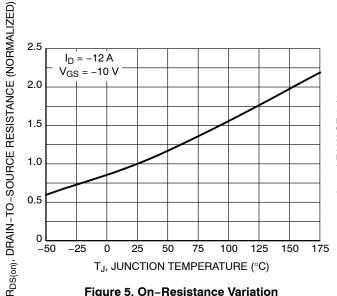


Figure 5. On–Resistance Variation with Temperature

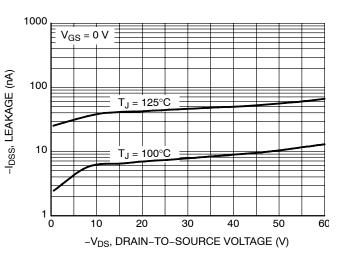
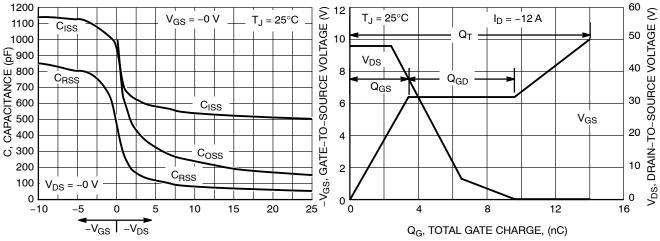


Figure 6. Drain-to-Source Leakage versus Voltage



GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (V)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

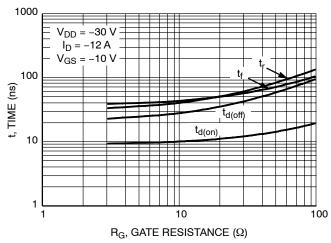


Figure 9. Resistive Switching Time Variation versus Gate Resistance

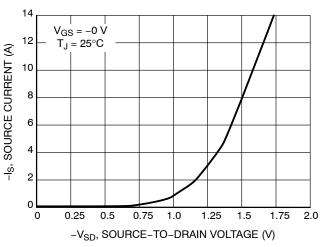


Figure 10. Diode Forward Voltage versus Current

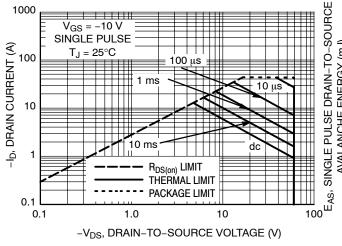


Figure 11. Maximum Rated Forward Biased Safe Operating Area

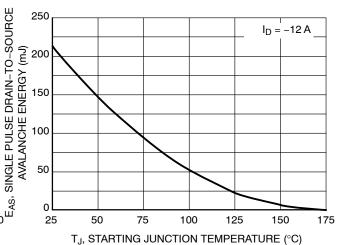
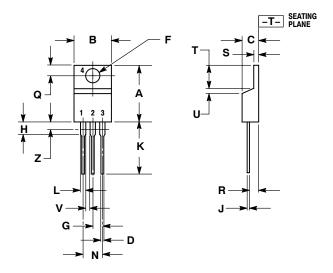


Figure 12. Maximum Avalanche Energy versus Starting Junction Temperature

PACKAGE DIMENSIONS

TO-220 **T SUFFIX** PLASTIC PACKAGE CASE 221A-09 **ISSUE AA**



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- T14:3M, 1902: CONTROLLING DIMENSION: INCH. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIM	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 5: PIN 1. GATE

DRAIN 2.

SOURCE

DRAIN

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